

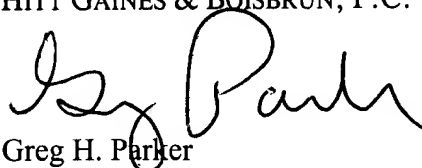
The references cited by the Examiner in previous Examiner's Actions fail, independently and in combination, to disclose, teach or suggest a first electrically isolated conductive trace formed at an outer region of a substrate and coupled to at least two of a plurality of bond pads, as recited in Claims 1 and 10 of the present application, as amended. In contrast, the independent references or a combination thereof merely teach conductive traces interconnected to the functional devices of integrated circuits.

For the foregoing reasons, applicant respectfully submits that the foregoing claims, as amended, are allowable. Therefore, a Notice of Allowance for Claims 1-3, 5-8 and 10-13 is respectfully requested. Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "Version with markings to show changes made."

Should it facilitate allowance of the application, the Examiner is invited to telephone the undersigned attorney.

Respectfully submitted,

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ATTORNEY DOCKET NO.: RA-AN 16-2

PATENT

**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

**IN THE CLAIMS:**

(1) Claim 1 has been amended as follows:

1. (Twice amended) An integrated circuit comprising:

a substrate;

a plurality of bond pads formed above the substrate; and

a first electrically isolated conductive trace formed at an outer region of the substrate and coupled to at least two of the plurality of bond pads.

(2) Claim 4 has been canceled without prejudice or disclaimer.

(3) Claim 10 has been amended as follows:

10. (Twice amended) An integrated circuit comprising:

a substrate;

a plurality of bond pads; and

an electrically isolated conductive tester runner formed on the substrate and around the plurality of bond pads, the isolated conductive tester runner electrically coupled to at least two of the plurality of bond pads.

(4) Claim 14 has been canceled without prejudice or disclaimer.